Annual General Meeting of Shareholders
May 15 2012

Chuck del Prado
President & CEO
Safe Harbor Statements

All matters discussed in this business and strategy update, except for any historical data, are forward-looking statements. Forward-looking statements involve risks and uncertainties that could cause actual results to differ materially from those in the forward-looking statements. These include, but are not limited to, economic conditions and trends in the semiconductor industry generally and the timing of the industry cycles specifically, currency fluctuations, the success of restructurings, the timing of significant orders, market acceptance of new products, competitive factors, litigation involving intellectual property, shareholder and other issues, commercial and economic disruption due to natural disasters, terrorist activity, armed conflict or political instability, epidemics and other risks indicated in the Company's filings from time to time with the U.S. Securities and Exchange Commission. All statements are made as of the date provided and we assume no obligation nor intend to update or revise any forward-looking statements to reflect future developments or circumstances.
• Semiconductor Equipment Market in 2011
• ASMI Results in 2011
• Status ASMI Back-end
  • Results
  • Products & Business highlights
• Status ASMI Front-end
  • Results
  • Products & Business highlights
• Market Outlook and Conclusions
• Semiconductor Equipment Market in 2011
• ASMI Results in 2011
• Status ASMI Back-end
  • Results
  • Products & Business highlights
• Status ASMI Front-end
  • Results
  • Products & Business highlights
• Market Outlook and Conclusions
• After strong recovery in 2010, our industry grew in 2011 to approximately the level of 2007
• Market softened in 2H of 2011
Assembly and Packaging Equipment spending declined in 2011 after a very strong 2010

Gartner March 2012
SMT Equipment Market 2011

Market Size $m – Q4 2011

SMT Equipment Market in 2011 flat compared to 2010

ASM SIPLACE Market Intelligence, Q4 2011
Wafer Fab Equipment grew in 2011

- 2011 WFE spending increased by 13%
- Logic and Foundry grew in 2011
- Memory declined

Gartner, March 2012
• Semiconductor Equipment Market in 2011
• ASMI Results in 2011
• Status ASMI Back-end
  • Results
  • Products & Business highlights
• Status ASMI Front-end
  • Results
  • Products & Business highlights
• Market Outlook and Conclusions
Key Highlights – 2011

- **Revenues up 34%**
  - Front-end grew 55%, especially (PE)ALD and EPI
  - Back-end increased 27%
  - ASM Assembly Systems (SMT) contributed €444m
- **Q4 Backlog of €331m (0.9 X Q4 sales)**
- **EBIT margin of 17%**
  - Front-end EBIT margin of 14% for full year
- **Cash flow from operations of €217m in 2011**
  - Proposal to ASMI AGM to increase dividend to €0.50 per share
- **Net earnings of €187m up from €111m in 2010**
  - Including gain on bargain purchase of €51m
  - Front-end and Back-end net profitable in all quarters
Historical development - Group

- Net Sales
- EBIT

<table>
<thead>
<tr>
<th>Quarter</th>
<th>07</th>
<th>08</th>
<th>09</th>
<th>10</th>
<th>11</th>
<th>12</th>
</tr>
</thead>
<tbody>
<tr>
<td>Net Sales in mln</td>
<td>€ 0</td>
<td>€ 50</td>
<td>€ 100</td>
<td>€ 150</td>
<td>€ 200</td>
<td>€ 250</td>
</tr>
<tr>
<td>EBIT in mln</td>
<td>€ 0</td>
<td>€ 50</td>
<td>€ 100</td>
<td>€ 150</td>
<td>€ 200</td>
<td>€ 250</td>
</tr>
</tbody>
</table>
## Net Earnings - Group

<table>
<thead>
<tr>
<th></th>
<th>Full Year 2010</th>
<th>Full Year 2011</th>
<th>Q1 2011</th>
<th>Q2 2011</th>
<th>Q3 2011</th>
<th>Q4 2011</th>
<th>Q1 2012</th>
</tr>
</thead>
<tbody>
<tr>
<td><strong>Front End</strong></td>
<td>293.4</td>
<td>456.1</td>
<td>116.1</td>
<td>121.7</td>
<td>104.1</td>
<td>114.2</td>
<td>94.8</td>
</tr>
<tr>
<td><strong>Back End</strong></td>
<td>929.5</td>
<td>1,178.3</td>
<td>316.1</td>
<td>352.4</td>
<td>272.1</td>
<td>237.8</td>
<td>216.2</td>
</tr>
<tr>
<td><strong>Net Sales</strong></td>
<td>1,222.9</td>
<td>1,634.3</td>
<td>432.2</td>
<td>474.1</td>
<td>376.1</td>
<td>352.0</td>
<td>311.0</td>
</tr>
<tr>
<td><strong>Front End</strong></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>as % of sales</td>
<td>39.1%</td>
<td>37.8%</td>
<td>39.2%</td>
<td>39.0%</td>
<td>39.0%</td>
<td>33.9%</td>
<td>33.0%</td>
</tr>
<tr>
<td><strong>Back End</strong></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>as % of sales</td>
<td>46.8%</td>
<td>34.8%</td>
<td>38.0%</td>
<td>37.6%</td>
<td>33.1%</td>
<td>28.3%</td>
<td>30.2%</td>
</tr>
<tr>
<td><strong>Gross Margin</strong></td>
<td>549.6</td>
<td>582.2</td>
<td>165.5</td>
<td>179.8</td>
<td>130.7</td>
<td>106.1</td>
<td>96.6</td>
</tr>
<tr>
<td>as % of sales</td>
<td>44.9%</td>
<td>35.6%</td>
<td>38.3%</td>
<td>37.9%</td>
<td>34.7%</td>
<td>30.2%</td>
<td>31.1%</td>
</tr>
<tr>
<td><strong>Selling, general and administrative</strong></td>
<td>(131.0)</td>
<td>(176.5)</td>
<td>(42.3)</td>
<td>(45.7)</td>
<td>(44.8)</td>
<td>(43.6)</td>
<td>(41.2)</td>
</tr>
<tr>
<td><strong>Research and development</strong></td>
<td>(78.8)</td>
<td>(129.4)</td>
<td>(29.5)</td>
<td>(30.0)</td>
<td>(34.6)</td>
<td>(35.3)</td>
<td>(33.5)</td>
</tr>
<tr>
<td><strong>Front End</strong></td>
<td>27.1</td>
<td>62.6</td>
<td>18.7</td>
<td>20.8</td>
<td>13.5</td>
<td>9.5</td>
<td>2.9</td>
</tr>
<tr>
<td><strong>Back End (100%)</strong></td>
<td>312.8</td>
<td>213.7</td>
<td>75.0</td>
<td>83.2</td>
<td>37.8</td>
<td>17.7</td>
<td>19.0</td>
</tr>
<tr>
<td><strong>EBIT (excl. restructuring/impairment)</strong></td>
<td>339.8</td>
<td>276.3</td>
<td>93.7</td>
<td>104.1</td>
<td>51.3</td>
<td>27.2</td>
<td>21.9</td>
</tr>
<tr>
<td>as % of sales</td>
<td>27.8%</td>
<td>16.9%</td>
<td>21.7%</td>
<td>22.0%</td>
<td>13.6%</td>
<td>7.7%</td>
<td>7.0%</td>
</tr>
<tr>
<td><strong>Restructuring</strong></td>
<td>(11.2)</td>
<td>-</td>
<td>-</td>
<td>-</td>
<td>-</td>
<td>-</td>
<td>-</td>
</tr>
<tr>
<td><strong>Bargain purchase (PPA)</strong></td>
<td>-</td>
<td>97.8</td>
<td>-</td>
<td>-</td>
<td>97.9</td>
<td>(0.1)</td>
<td>-</td>
</tr>
<tr>
<td><strong>Impairment</strong></td>
<td>-</td>
<td>(8.0)</td>
<td>-</td>
<td>-</td>
<td>-</td>
<td>(8.0)</td>
<td>-</td>
</tr>
<tr>
<td><strong>Front End</strong></td>
<td>(35.7)</td>
<td>44.5</td>
<td>7.0</td>
<td>16.4</td>
<td>12.6</td>
<td>8.6</td>
<td>(2.5)</td>
</tr>
<tr>
<td><strong>Back End (ASMI interest)</strong></td>
<td>146.3</td>
<td>142.2</td>
<td>33.1</td>
<td>33.9</td>
<td>68.4</td>
<td>6.8</td>
<td>8.8</td>
</tr>
<tr>
<td><strong>Net Result</strong></td>
<td>110.6</td>
<td>186.8</td>
<td>40.1</td>
<td>50.3</td>
<td>81.0</td>
<td>15.4</td>
<td>6.3</td>
</tr>
</tbody>
</table>
Decreasing working capital in Front-end and Back-end due to lower activity levels
## Cash Flow - Group

<table>
<thead>
<tr>
<th>€ million</th>
<th>Full Year 2010</th>
<th>Full Year 2011</th>
<th>Q1 2011</th>
<th>Q2 2011</th>
<th>Q3 2011</th>
<th>Q4 2011</th>
<th>Q1 2012</th>
</tr>
</thead>
<tbody>
<tr>
<td>Net result</td>
<td>242.5</td>
<td>316.2</td>
<td>70.2</td>
<td>81.1</td>
<td>143.2</td>
<td>21.7</td>
<td>12.6</td>
</tr>
<tr>
<td>Depreciation</td>
<td>35.8</td>
<td>49.5</td>
<td>12.6</td>
<td>11.2</td>
<td>12.4</td>
<td>13.2</td>
<td>13.1</td>
</tr>
<tr>
<td>Working Capital</td>
<td>(88.9)</td>
<td>(39.2)</td>
<td>47.1</td>
<td>(97.9)</td>
<td>(7.3)</td>
<td>18.9</td>
<td>21.9</td>
</tr>
<tr>
<td>Restructuring &amp; impairments</td>
<td>(7.4)</td>
<td>4.9</td>
<td>(1.7)</td>
<td>(0.8)</td>
<td>(0.6)</td>
<td>7.9</td>
<td>0.2</td>
</tr>
<tr>
<td>Others</td>
<td>75.9</td>
<td>(114.7)</td>
<td>(9.5)</td>
<td>7.4</td>
<td>(90.9)</td>
<td>(21.7)</td>
<td>(9.8)</td>
</tr>
<tr>
<td><strong>Net cash from operating activities</strong></td>
<td><strong>259.9</strong></td>
<td><strong>216.6</strong></td>
<td><strong>118.8</strong></td>
<td><strong>1.1</strong></td>
<td><strong>56.8</strong></td>
<td><strong>40.0</strong></td>
<td><strong>38.5</strong></td>
</tr>
<tr>
<td>Net cash from investing activities</td>
<td>(100.6)</td>
<td>(70.0)</td>
<td>1.0</td>
<td>(26.0)</td>
<td>(21.7)</td>
<td>(23.3)</td>
<td>(18.4)</td>
</tr>
<tr>
<td>Net cash from financing activities</td>
<td>(123.0)</td>
<td>(78.5)</td>
<td>(1.4)</td>
<td>(64.0)</td>
<td>(35.3)</td>
<td>22.1</td>
<td>(4.1)</td>
</tr>
<tr>
<td>Exchange rate effects</td>
<td>10.1</td>
<td>(18.1)</td>
<td>(13.1)</td>
<td>1.9</td>
<td>(7.7)</td>
<td>0.8</td>
<td>(1.6)</td>
</tr>
<tr>
<td><strong>Net increase (decrease) in cash and cash equivalents</strong></td>
<td><strong>46.4</strong></td>
<td><strong>50.0</strong></td>
<td><strong>105.2</strong></td>
<td><strong>(87.0)</strong></td>
<td><strong>(7.8)</strong></td>
<td><strong>39.6</strong></td>
<td><strong>14.4</strong></td>
</tr>
</tbody>
</table>
## Balance Sheet - Group

<table>
<thead>
<tr>
<th></th>
<th></th>
<th></th>
<th></th>
<th></th>
<th></th>
<th></th>
</tr>
</thead>
<tbody>
<tr>
<td>Cash and cash equivalents</td>
<td>340</td>
<td>445</td>
<td>358</td>
<td>351</td>
<td>390</td>
<td>405</td>
</tr>
<tr>
<td>Other current assets</td>
<td>594</td>
<td>802</td>
<td>844</td>
<td>829</td>
<td>806</td>
<td>773</td>
</tr>
<tr>
<td>Property, plant and equipment, net</td>
<td>198</td>
<td>210</td>
<td>224</td>
<td>250</td>
<td>260</td>
<td>259</td>
</tr>
<tr>
<td>Goodwill, net</td>
<td>51</td>
<td>48</td>
<td>48</td>
<td>50</td>
<td>52</td>
<td>51</td>
</tr>
<tr>
<td>Other Assets</td>
<td>31</td>
<td>52</td>
<td>56</td>
<td>67</td>
<td>74</td>
<td>74</td>
</tr>
<tr>
<td><strong>Total Assets</strong></td>
<td><strong>1,214</strong></td>
<td><strong>1,558</strong></td>
<td><strong>1,530</strong></td>
<td><strong>1,546</strong></td>
<td><strong>1,582</strong></td>
<td><strong>1,561</strong></td>
</tr>
<tr>
<td>ST debt (incl current LT debt)</td>
<td>81</td>
<td>27</td>
<td>37</td>
<td>35</td>
<td>45</td>
<td>40</td>
</tr>
<tr>
<td>Other current liabilities</td>
<td>344</td>
<td>641</td>
<td>597</td>
<td>462</td>
<td>418</td>
<td>409</td>
</tr>
<tr>
<td>Long-term debt &amp; Convertible subordinated debt</td>
<td>135</td>
<td>134</td>
<td>135</td>
<td>135</td>
<td>150</td>
<td>150</td>
</tr>
<tr>
<td>Other long term liabilities</td>
<td>7</td>
<td>10</td>
<td>10</td>
<td>11</td>
<td>11</td>
<td>11</td>
</tr>
<tr>
<td><strong>Total Liabilities</strong></td>
<td><strong>567</strong></td>
<td><strong>813</strong></td>
<td><strong>778</strong></td>
<td><strong>642</strong></td>
<td><strong>625</strong></td>
<td><strong>610</strong></td>
</tr>
<tr>
<td>Total Shareholders' Equity</td>
<td>411</td>
<td>490</td>
<td>520</td>
<td>625</td>
<td>660</td>
<td>653</td>
</tr>
<tr>
<td>Non-controlling interest</td>
<td>236</td>
<td>255</td>
<td>232</td>
<td>279</td>
<td>298</td>
<td>298</td>
</tr>
<tr>
<td><strong>Total Liabilities and Equity</strong></td>
<td><strong>1,214</strong></td>
<td><strong>1,558</strong></td>
<td><strong>1,530</strong></td>
<td><strong>1,546</strong></td>
<td><strong>1,582</strong></td>
<td><strong>1,561</strong></td>
</tr>
</tbody>
</table>
Book-to-bill ratio in 2011 of 0.8 (2010 was 1.2), book-to-bill ratio of 1.2 in Q1 2012

Backlog decreased from €500m at the end of 2010, to €331m at the end of 2011 but increased to €373m in Q1 2012
## Use of ASM PT Dividends

<table>
<thead>
<tr>
<th>Year</th>
<th>Dividends</th>
<th>ASMI shares</th>
<th>Convertible Bonds</th>
<th>Dividend</th>
<th>Balance</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>€ million</td>
<td>Received</td>
<td>Repurchased</td>
<td>Repurchased</td>
<td>pay outs</td>
</tr>
<tr>
<td>2007</td>
<td>49.1</td>
<td>-32.9</td>
<td>-5.4</td>
<td>10.8</td>
<td></td>
</tr>
<tr>
<td>2008</td>
<td>49.1</td>
<td>-36.5</td>
<td>-27.1</td>
<td>-14.5</td>
<td></td>
</tr>
<tr>
<td>2009</td>
<td>21.4</td>
<td>-27.0</td>
<td>9.8</td>
<td></td>
<td></td>
</tr>
<tr>
<td>2010</td>
<td>65.6</td>
<td>-55.8</td>
<td>-22.3</td>
<td>64.9</td>
<td></td>
</tr>
<tr>
<td>2011</td>
<td>87.2</td>
<td>-13.4</td>
<td>-28.0</td>
<td>-41.4</td>
<td></td>
</tr>
<tr>
<td>2012 (as per May 15)</td>
<td>-49.9</td>
<td>-142.8</td>
<td>-55.7</td>
<td>24.0</td>
<td></td>
</tr>
<tr>
<td>Total</td>
<td>272.4</td>
<td>-49.9</td>
<td>-142.8</td>
<td>-55.7</td>
<td>24.0</td>
</tr>
</tbody>
</table>
• ASMI share price declined 19% in 2011, but recovered in Jan’12
• Comparison same sector companies
ASMI Share Price last 5 years

ASMI share price increased 40% (end of 2011) compared to 2007

Source: google.com/finance
Global Sustainability

Health and Safety

Recordable Case Rate (CY)

2009 2010 2011

0.52 0.62 0.47

0.62 0.47 0.46

0.47 0.33

Environment

ASM Front-end: Sustained Power Consumption Reductions Despite Increased Activity

ASM FE Power Consumption
Global Reduction vs. 2007 Baseline

2008 2009 2010 2011

0% 5% 10% 15% 20% 25%

ASM Back-end Recycled Water:
2010 = 35.7%, 2011 = 37.7%

2012-2013 Focus on Enhancing Design For
EHS in ASM Front-end

ASM Front-end targets Global ISO14001 by 2013; ASM Back-end aims for Recycled Water percentage above 40% in 2012
### Sustainable Applications/Products

**2011:**
- Front-end and Back-end supplier to LED market
- ASM Front-end EPI for power management solutions
- ASM Back-end entered solar market
- ASM Back-end Wire bonders for power devices

### Code Of Conduct

**2011 Performance: Continued Progress**

ASM Front-end:
- Ethics Committee Established Q1 2012
- Suppliers Identified for CY2012-13 Audits

ASM Back-end:
- Self-assessments 3 main Asia/China sites

**2012-2013 Plans:**

ASM Front-end:
- Corporate Labor Management Policy
- Company-Wide Ethics Training
- EICC in Supplier Master Agreement

ASM Back-end:
- Third-party audit
- Self-assessment other plants

**Publish aspects of Sustainability on ASM website by end 2012**
• Semiconductor Equipment Market in 2011
• ASMI Results in 2011
• **Status ASMI Back-end**
  • Results
  • Products & Business highlights
• **Status ASMI Front-end**
  • Results
  • Products & Business highlights
• **Market Outlook and Conclusions**
• Sales impacted by ASM Assembly Systems (SMT) and decline of market
• EBIT impacted by lower sales and mix changes
2011: Downward sales trend leading to lower EBIT%

<table>
<thead>
<tr>
<th>€ million</th>
<th>Full Year 2010</th>
<th>Full Year 2011</th>
<th>Q1 2011</th>
<th>Q2 2011</th>
<th>Q3 2011</th>
<th>Q4 2011</th>
<th>Q1 2012</th>
</tr>
</thead>
<tbody>
<tr>
<td>Net Sales</td>
<td>929.5</td>
<td>1,178.3</td>
<td>316.1</td>
<td>352.4</td>
<td>272.1</td>
<td>237.8</td>
<td>216.2</td>
</tr>
<tr>
<td>Gross Margin</td>
<td>435.0</td>
<td>409.8</td>
<td>120.0</td>
<td>132.4</td>
<td>90.1</td>
<td>67.4</td>
<td>65.3</td>
</tr>
<tr>
<td>as % of sales</td>
<td>46.8%</td>
<td>34.8%</td>
<td>38.0%</td>
<td>37.6%</td>
<td>33.1%</td>
<td>28.3%</td>
<td>30.2%</td>
</tr>
<tr>
<td>Selling, general and administrative</td>
<td>(79.9)</td>
<td>(115.3)</td>
<td>(26.8)</td>
<td>(29.6)</td>
<td>(30.0)</td>
<td>(28.8)</td>
<td>(26.6)</td>
</tr>
<tr>
<td>Research and development</td>
<td>(42.3)</td>
<td>(80.9)</td>
<td>(18.2)</td>
<td>(19.5)</td>
<td>(22.3)</td>
<td>(20.9)</td>
<td>(19.7)</td>
</tr>
<tr>
<td>EBIT (excl. impairment)</td>
<td>312.8</td>
<td>213.7</td>
<td>75.0</td>
<td>83.2</td>
<td>37.8</td>
<td>17.7</td>
<td>19.0</td>
</tr>
<tr>
<td>as % of sales</td>
<td>33.6%</td>
<td>18.1%</td>
<td>23.7%</td>
<td>23.6%</td>
<td>13.9%</td>
<td>7.4%</td>
<td>8.8%</td>
</tr>
<tr>
<td>Bookings</td>
<td>1,113</td>
<td>971</td>
<td>323</td>
<td>256</td>
<td>219</td>
<td>173</td>
<td>282</td>
</tr>
<tr>
<td>Book-to-Bill</td>
<td>1.2</td>
<td>0.8</td>
<td>1.0</td>
<td>0.7</td>
<td>0.8</td>
<td>0.7</td>
<td>1.3</td>
</tr>
</tbody>
</table>
Bookings & Backlog – Back-end

Book-to-bill ratio in 2011 was 0.8. Q1 2012 shows improved book-to-bill ratio of 1.3

Backlog declined 33% to €226m in 2011, but increased to €284m at the end of Q1 2012
IC manufacturing - LED manufacturing - Surface Mount Technology

### Market

**IC manufacturing**
- Assembly tools
- Packaging tools
- Inspection tools
- Test handling tools

**LED manufacturing**
- Assembly tools
- Die & package sorting tools
- Packaging tools
- Testing tools

### Application

**IC manufacturing**
- Die bonding
- Flip chip bonding
- Wire bonding
- Moulding
- Trim & Form, singulation
- Vision and Inspection
- Test Handler
- In-line automation
- L/F

**LED manufacturing**
- Die sorting
- Die bonding
- Wire bonding
- Die coating
- Encapsulation
- Singulation
- Package sorting
- Testing
- L/F

**SMT**
- Placement tools
- Software solution

### ASM Relative Positioning

**IC manufacturing**
- #1 in the equipment market since 2002
- Qualified by most IDM’s and Subcontractors
- Strong process and package know how
- Strong local service and support organization

**LED manufacturing**
- #1 in the equipment market
- Total solution approach
- Strong process and package know how
- Strong local service and support organization

**SMT**
- ASM #3 worldwide, #1 in Europe with >50% market share
- Leading position in High-end tools
- Strong software solution

© 2009 ASM
Confidential and Proprietary Information
ASM Back-end Product Highlights

GoCu™ Wire Bonder

- No loss of UPH in Au to Cu conversion
- Dual wire clamper improves Mean Time Between Assistance (MTBA)
- Auto Pattern Recognition (PR) & Auto Looping
ASM Back-end Product Highlights

- Key Value Drivers for SIPLACE DX Placement Machine
  - Price/Performance
  - Low Cost-Of-Ownership
  - Robustness and Ease of Use
  - Widest Application on a Single Platform
- Recently won a few Product Awards in Asia/China
• Acquisition of SMT business raised ASMPT revenue to new record of €1,178m

• Addition SMT business further contributes to ASMPT strength of diversified customer base

• Strengthened product portfolio in the copper market

• Grew Chengdu and added Munich R&D center, now more than 1,000 highly qualified R&D engineers worldwide in four R&D centers
- Integrated the former SEAS organisation (SMT)
- Revenue of €444m million in 2011, growth 18%
- Introduced DX series placement machine for Asian market
• #1 position in the IC Assembly & Packaging market since 2002

• Widest product portfolio, ASMPT the only total solution provider

• ASMPT has the largest customer base in China

• ASMPT has a leadership position in the LED market

• SMT provides further growth opportunities
Outline

• Semiconductor Equipment Market in 2011
• ASMI Results in 2011
• Status ASMI Back-end
  • Results
  • Products & Business highlights
• Status ASMI Front-end
  • Results
  • Products & Business highlights
• Market Outlook and Conclusions
• Front-end strong year in 2011
• Positive EBIT from Q2 2010 onwards
Stable quarterly performance during 2011, last quarters impacted by mix and efficiency

<table>
<thead>
<tr>
<th></th>
<th>€ million</th>
<th></th>
<th></th>
<th></th>
<th></th>
<th>Q4 2011</th>
<th>Q1 2012</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>2010</td>
<td>2011</td>
<td>Q1 2011</td>
<td>Q2 2011</td>
<td>Q3 2011</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Net Sales</td>
<td>293.4</td>
<td>456.1</td>
<td>116.1</td>
<td>121.7</td>
<td>104.1</td>
<td>114.2</td>
<td>94.8</td>
</tr>
<tr>
<td>Gross Margin</td>
<td>114.6</td>
<td>172.3</td>
<td>45.6</td>
<td>47.4</td>
<td>40.6</td>
<td>38.8</td>
<td>31.3</td>
</tr>
<tr>
<td>as % of sales</td>
<td>39.1%</td>
<td>37.8%</td>
<td>39.2%</td>
<td>39.0%</td>
<td>39.0%</td>
<td>33.9%</td>
<td>33.0%</td>
</tr>
<tr>
<td>Selling, general and administrative</td>
<td>(51.0)</td>
<td>(61.2)</td>
<td>(15.5)</td>
<td>(16.1)</td>
<td>(14.8)</td>
<td>(14.8)</td>
<td>(14.6)</td>
</tr>
<tr>
<td>Research and development</td>
<td>(36.5)</td>
<td>(48.5)</td>
<td>(11.3)</td>
<td>(10.5)</td>
<td>(12.2)</td>
<td>(14.5)</td>
<td>(13.8)</td>
</tr>
<tr>
<td>EBIT (excl. restructuring)</td>
<td>27.1</td>
<td>62.6</td>
<td>18.7</td>
<td>20.8</td>
<td>13.5</td>
<td>9.5</td>
<td>2.9</td>
</tr>
<tr>
<td>as % of sales</td>
<td>9.2%</td>
<td>13.7%</td>
<td>16.1%</td>
<td>17.1%</td>
<td>13.0%</td>
<td>8.3%</td>
<td>3.0%</td>
</tr>
<tr>
<td>Bookings</td>
<td>405</td>
<td>398</td>
<td>121</td>
<td>84</td>
<td>93</td>
<td>100</td>
<td>81</td>
</tr>
<tr>
<td>Book-to-Bill</td>
<td>1.4</td>
<td>0.9</td>
<td>1.0</td>
<td>0.7</td>
<td>0.9</td>
<td>0.9</td>
<td>0.8</td>
</tr>
</tbody>
</table>
Backlog decreased quarter over quarter to €89m in Q1 2012
Book-to-bill ratio in 2011 of 0.9
ASM Products – Front-end

Market Requirements: 32nm → 22nm → 14nm and beyond

**Process**

<table>
<thead>
<tr>
<th>ALD and PEALD</th>
<th>Application</th>
<th>ASM Relative Positioning</th>
</tr>
</thead>
<tbody>
<tr>
<td>ALD solution (Hafnium oxide)</td>
<td>ALD key for High-k Gate technology</td>
<td>#1 in the served ALD market</td>
</tr>
<tr>
<td>PEALD Low temp dielectrics</td>
<td>SDDP-application of PE-ALD</td>
<td>Qualified by nearly all Logic manufacturers</td>
</tr>
<tr>
<td>Diffusion Furnace</td>
<td>3D FinFET requires more conformal layers, strength of ALD</td>
<td>Strengthening inroads into Memory with PEALD</td>
</tr>
<tr>
<td>Advanced batch processing</td>
<td>Smallest footprint per reactor</td>
<td>Leading IC manufacturers are customers</td>
</tr>
<tr>
<td>Unique “dual reactor dual boat” design</td>
<td>Lowest Cost of Ownership</td>
<td></td>
</tr>
</tbody>
</table>

**Application**

<table>
<thead>
<tr>
<th>Epitaxy</th>
<th>Application</th>
</tr>
</thead>
<tbody>
<tr>
<td>Epitaxial films for NMOS/PMOS</td>
<td>Affordable method of high quality crystal growth</td>
</tr>
<tr>
<td>Epitaxial films for analog devices</td>
<td>Thick Epi layers for power devices</td>
</tr>
</tbody>
</table>

| PECVD | |
| Extreme low-k films | Advanced intermetal dielectric film |

**PECVD**

| Strong IP protected portfolio |

© 2009 ASM
Confidential and Proprietary Information
• Front-end revenue grew by 55%
• Reached milestone of shipping 500\textsuperscript{th} atomic layer deposition (ALD) reactor for use in semiconductor manufacturing
• Expanded the number of (PE)ALD applications qualified for High Volume Manufacturing
• Seeded the market with systems to develop new applications
• Successfully demonstrated a new 14nm high-k gate dielectric, enabling the further scaling of high-k metal gate technology using ASM’s Pulsar module
ASM Revenue %

Key Developments:

- Diversification of customer base from Logic to Memory and Foundries
- Momentum Asia growing
ASM Front-end’s Competitive Advantages

- Established a leading position in ALD technology, since start in 1999
- Industry shift from Planar Logic to 3D FinFET will require more ALD/PEALD
- Alternate Memory devices also likely to require more ALD/PEALD
- ASMI is one of the two leading suppliers of Low-k films
- In the EPI market ASMI is one of only two global suppliers
- ASM’s Vertical Furnace has leading IC manufacturers as customers
• Semiconductor Equipment Market in 2011
• ASMI Results in 2011
• Status ASMI Back-end
  • Results
  • Products & Business highlights
• Status ASMI Front-end
  • Results
  • Products & Business highlights
• Market Outlook and Conclusions
Semi Capital Equipment Outlook

Market predicted to be down in 2012 by approximately 12%

Semi Capital Equipment Year to Year Growth

<table>
<thead>
<tr>
<th>Period</th>
<th>Growth</th>
</tr>
</thead>
<tbody>
<tr>
<td>2007-2008</td>
<td>-31.7%</td>
</tr>
<tr>
<td>2008-2009</td>
<td>-45.4%</td>
</tr>
<tr>
<td>2009-2010</td>
<td>+142.7%</td>
</tr>
<tr>
<td>2010-2011</td>
<td>+8.4%</td>
</tr>
<tr>
<td>2011-2012</td>
<td>-11.6%</td>
</tr>
<tr>
<td>2012-2013</td>
<td>+10.5%</td>
</tr>
</tbody>
</table>

Gartner Mar 2012
Applications driving growth

- Mobile devices, smartphones, media tablets and Solid State drives
- Growing worldwide consumer base using these mobile devices
- General lighting for LED

- 22nm technology node signifies important inflection
- Alternate Memory devices being explored
- 2.5D interposer products
- High-density packages
- Copper wire bonding
- Higher placement count SMT equipment
Assembly and Packaging Equipment spending is expected to slightly decline in 2012, and to rebound in 2013.
SMT Equipment spending is expected to be down 14% in 2012, up 20% in 2013
LED – A High Growth Back End Market Segment (Not Equipment)

Key Growth Drivers:

For LED Equipment:

- LEDs provide an energy efficient, high quality and longer life alternative to traditional light sources
- Growth expected when LEDs penetrate the large general illumination market

Source: Morgan Stanley Equity Research (2012)
Wafer Fab Equipment Forecast by technology node

Market Forecast shows growth in advanced technology nodes

Gartner March, 2012
Based upon the current backlog and our current visibility:

- We expect in the current quarter our Front-end segment to show a single digit sales decrease and a strong order intake.
- In our Back-end segment we foresee, based upon the current backlog, a sales increase in the current quarter.
Summary

- Back-end continued #1 position in IC Assembly & Packaging market
- Acquisition of SMT business raised Back-end revenue to new record of €1,178m in 2011
- Front-end revenue growth of 55%, leading revenue growth amongst competitors
- Front-end and Back-end net profitable in all quarters of 2011
- Front-end and Back-end well positioned for industry shifts to more advanced device structures and growth markets
- Proposal to May 2012 Annual Shareholders Meeting to increase dividend payment